

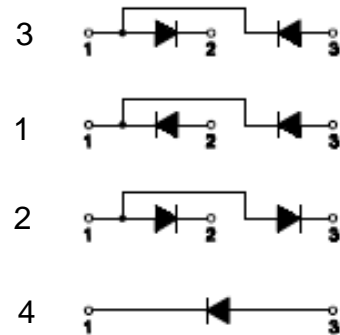
### Features

- Blocking voltage: 800 to 2000V
- Heat transfer through aluminum oxide DBC Ceramic isolated metal baseplate
- Industrial standard package
- Thick copper baseplate
- 2500 V<sub>RMS</sub> isolating voltage

### Typical Applications

- Power Supplies
- AC&DC Motor Drivers
- Bridge Circuits
- Welders
- Battery Supplier

A



### Module Type

Type	V <sub>DRM</sub>	V <sub>RSM</sub>
JA1/JA2/JA3/JA4M90-80	800V	900V
JA1/JA2/JA3/JA4M90-120	1200V	1300V
JA1/JA2/JA3/JA4M90-160	1600V	1700V
JA1/JA2/JA3/JA4M90-180	1800V	1900V
JA1/JA2/JA3/JA4M90-200	2000V	2100V

### Maximum Ratings

Parameters	Symbol	Test Conditions	Values	Unit
State the average current	I <sub>F(AV)</sub>	Single phase ,half wave 180°conduction T <sub>c</sub> =85°C	90	A
Surge forward current	I <sub>FSM</sub>	t=10mS T <sub>J</sub> =45°C	2000	A
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	t=10mS T <sub>J</sub> =45°C	20000	A <sup>2</sup> s
Isolation Breakdown Voltage(R.M.S)	Visol	Ac.50Hz; R.M.S; 1min	2500	V
		Ac.50Hz; R.M.S; 1sec	3500	V
Operating Junction Temperature	T <sub>J</sub>		-40~+150	°C
Storage Temperature	T <sub>stg</sub>		-40~+125	°C

Mounting Torque	Mt	To terminals(M5)	$3 \pm 15\%$	Nm
	Ms	To heatsink(M6)	$5 \pm 15\%$	
Module(Approximately)	Weight		100	g

## Electrical Characteristics

Parameters	Symbol	Test Conditions	Values			Unit
			Min.	Typ.	Max.	
Maximum Forward voltage drop	$V_{FM}$	$T=25^{\circ}\text{C}$ $I_F=90\text{A}$	—	0.95	1.05	V
Maximum Repetitive Peak Reverse Current	$I_{RRM}$	$T_J=25^{\circ}\text{C}$ $V_{RD}=V_{RRM}$	—	—	20	$\mu\text{A}$
		$T_J=150^{\circ}\text{C}$ $V_{RD}=V_{RRM}$	—	—	5	mA

## Thermal Characteristics

Parameters	Symbol	Test Conditions	Values	Unit
Maximum internal thermal resistance, junction to case per leg	$R_{th(J-C)}$	Per diode	0.35	$^{\circ}\text{C}/\text{W}$
Typical thermal resistance, case to heatsink per module	$R_{th(C-S)}$	Module	0.1	$^{\circ}\text{C}/\text{W}$

## Performance Curves

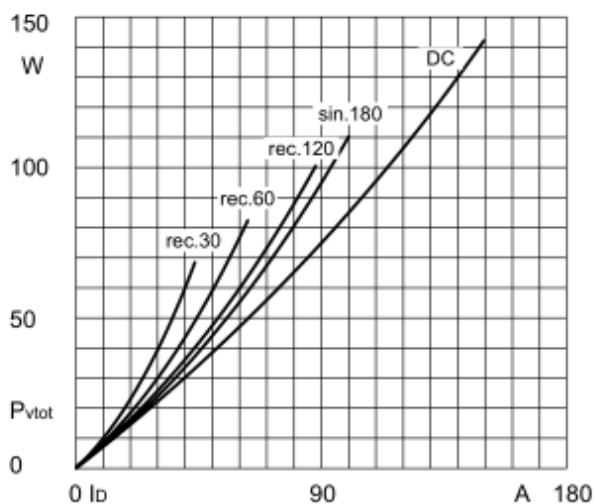


Fig1. Power dissipation

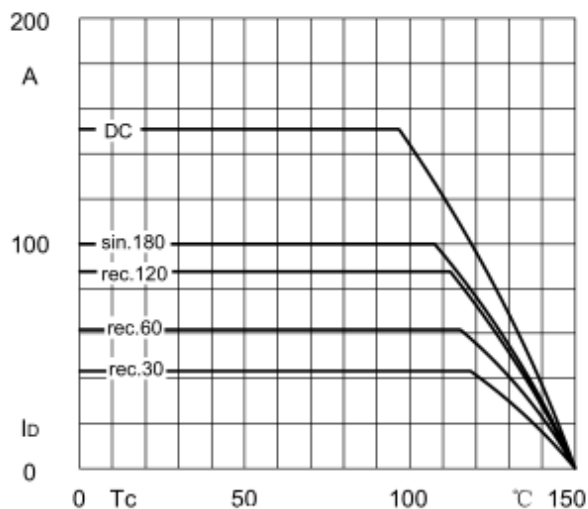


Fig2. Forward Current Derating Curve

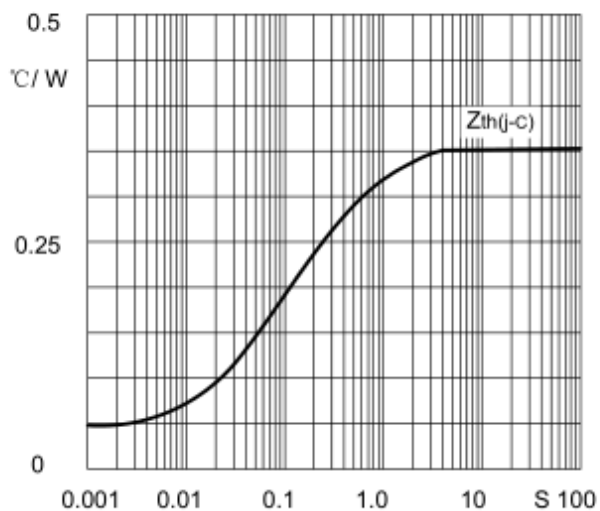


Fig3. Transient thermal impedance

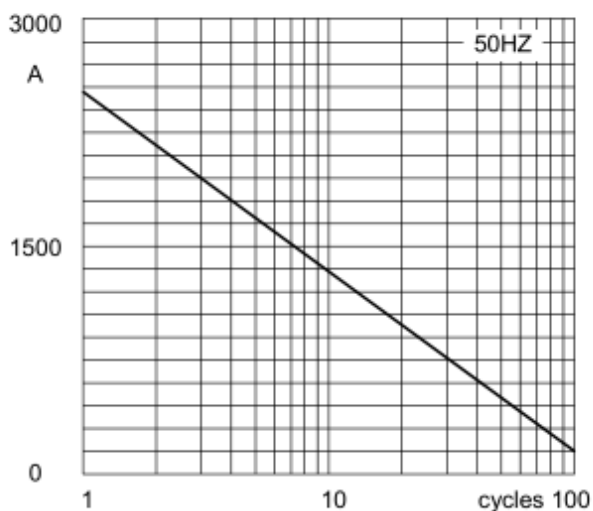


Fig4. Max Non-Repetitive Forward Surge Current

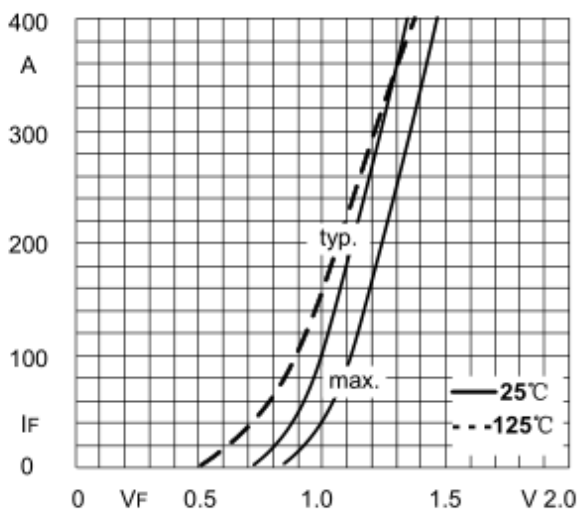


Fig5. Forward Characteristics

## Ordering Information Tabel

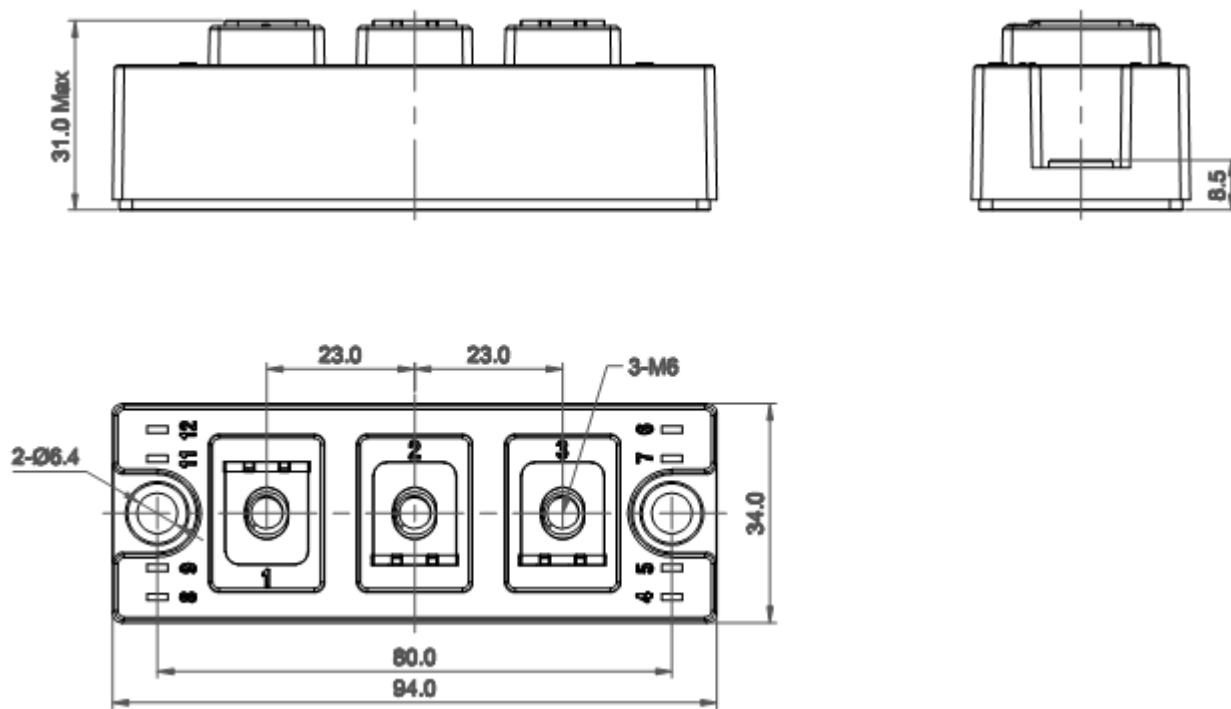
### Device code

J	A1M	90	-	160
①	②	③		④

- ① JH's power module
- ② Circuit configuration, M-High Power Products Diode Modules
- ③ Maximum average forward current, A
- ④ Voltage code 1600v

## Package Outline Information

### A PACKAG



Dimensions in mm

## Friendship Reminder

- JiNan JingHeng (hereinafter referred to as JH) reserves the right to make changes to this document and its products and specifications at anytime without notice.
- Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
- JH makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does JH assume any liability for application assistance or customer product design.
- JH does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.
- No license is granted by implication or otherwise under any intellectual property rights of JH.
- JH's products are not authorized for use as critical components in life support devices or systems without express written approval of JH.